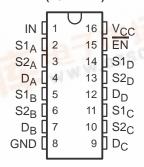
QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH WITH I OW ON-STATE RESISTANCE

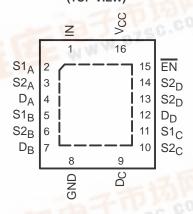
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- Low Differential Gain and Phase
 (D_G = 0.82%, D_P = 0.1 Degree Typ)
- Wide Bandwidth (BW = 300 MHz Min)
- Low Crosstalk (X_{TALK} = −80 dB Typ)
- Low Power Consumption (I_{CC} = 10 μA Max)
- Bidirectional Data Flow, With Near-Zero Propagation Delay
- Low ON-State Resistance ($r_{on} = 3 \Omega \text{ Typ}$)
- Rail-to-Rail Switching on Data I/O Ports (0 to V_{CC})
- V_{CC} Operating Range From 3 V to 3.6 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Data and Control Inputs Provide Undershoot Clamp Diode
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- Suitable for Both RGB and Composite-Video Switching

D, DBQ, DGV, OR PW PACKAGE (TOP VIEW)



RGY PACKAGE (TOP VIEW)



description/ordering information

The TI TS3V330 video switch is a 4-bit 1-of-2 multiplexer/demultiplexer with a single switch-enable (\overline{EN}) input. When \overline{EN} is low, the switch is enabled and the D port is connected to the S port. When \overline{EN} is high, the switch is disabled and the high-impedance state exists between the D and S ports. The select (IN) input controls the data path of the multiplexer/demultiplexer.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Tape and reel	TS3V330RGYR	TF330
–40°C to 85°C	0010 5	Tube	TS3V330D	TONIONE
	SOIC – D	Tape and reel	TS3V330DR	TS3V330
	SSOP (QSOP) – DBQ	Tape and reel	TS3V330DBQR	TF330
	TOOOD DW	Tube	TS3V330PW	TEOO
	TSSOP – PW	Tape and reel	TS3V330PWR	TF330
	TVSOP - DGV	Tape and reel	TS3V330DGVR	TF330

Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TS3V330 QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH WITH LOW ON-STATE RESISTANCE

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description/ordering information (continued)

Low differential gain and phase make this switch ideal for composite and RGB video applications. This device has wide bandwidth and low crosstalk, making it suitable for high-frequency applications as well.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. This switch maintains isolation during power off.

To ensure the high-impedance state during power up or power down, \overline{EN} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

INP	JTS	INPUT/OUTPUT	FUNCTION		
EN	IN	D	FUNCTION		
L	L	S1	D port = S1 port		
L	Н	S2	D port = S2 port		
Н	Χ	Z	Disconnect		

PIN DESCRIPTIONS

PIN NAME	DESCRIPTION
S1, S2	Analog video I/Os
D	Analog video I/Os
IN	Select input
EN	Switch-enable input



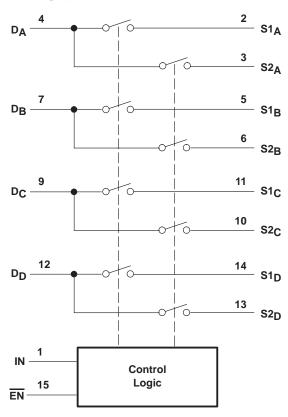
TS3V330 QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH WITH LOW ON-STATE RESISTANCE SCDS162B - MAY 2004 - REVISED OCTOBER 2004

PARAMETER DEFINITIONS

PARAMETER	DESCRIPTION
RON	Resistance between the D and S ports, with the switch in the ON state
loz	Output leakage current measured at the D and S ports, with the switch in the OFF state
IOS	Short-circuit current measured at the I/O pins
VIN	Voltage at the IN pin
V _{EN}	Voltage at the EN pin
C _{IN}	Capacitance at the control (EN, IN) inputs
COFF	Capacitance at the analog I/O port when the switch is OFF
CON	Capacitance at the analog I/O port when the switch is ON
VIH	Minimum input voltage for logic high for the control (EN, IN) inputs
VIL	Minimum input voltage for logic low for the control (EN, IN) inputs
VH	Hysteresis voltage at the control (EN, IN) inputs
VIK	I/O and control (EN, IN) inputs diode clamp voltage
VI	Voltage applied to the D or S pins when D or S is the switch input
Vo	Voltage applied to the D or S pins when D or S is the switch output
lіН	Input high leakage current of the control (EN, IN) inputs
IIL	Input low leakage current of the control (EN, IN) inputs
IJ	Current into the D or S pins when D or S is the switch input
ΙO	Current into the D or S pins when D or S is the switch output
l _{off}	Output leakage current measured at the D or S ports, with $V_{CC} = 0$
tON	Propagation delay measured between 50% of the digital input to 90% of the analog output when switch is turned ON
^t OFF	Propagation delay measured between 50% of the digital input to 90% of the analog output when switch is turned OFF
BW	Frequency response of the switch in the ON state measured at -3 dB
X _{TALK}	Unwanted signal coupled from channel to channel. Measured in $-dB$. $X_{TALK} = 20 \log V_O/V_I$. This is a nonadjacent crosstalk.
O _{IRR}	Off isolation is the resistance (measured in -dB) between the input and output with the switch OFF.
D _G	Magnitude variation between analog input and output pins when the switch is ON and the dc offset of composite video signal varies at the analog input pin. In the NTSC standard, the frequency of the video signal is 3.58 MHz, and dc offset is from 0 to 0.714 V.
Dp	Phase variation between analog input and output pins when the switch is ON and the dc offset of composite-video signal varies at the analog input pin. In the NTSC standard, the frequency of the video signal is 3.58 MHz, and dc offset is from 0 to 0.714 V.
Icc	Static power-supply current
ICCD	Variation of I _{CC} for a change in frequency in the control (EN, IN) inputs
ΔlCC	This is the increase in supply current for each control input that is at the specified voltage level, rather than VCC or GND.

TS3V330 QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH WITH LOW ON-STATE RESISTANCE SCDS162B - MAY 2004 - REVISED OCTOBER 2004

functional diagram (positive logic)



TS3V330 QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH WITH LOW ON-STATE RESISTANCE

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range Vala	0 5 V/ to 4 6 V/
Supply voltage range, V _{CC}	
Control input voltage range, V _{IN} (see Notes 1 and 2)	0.5 V to 4.6 V
Switch I/O voltage range, V _{I/O} (see Notes 1, 2, and 3)	. -0.5 V to 4.6 V
Control input clamp current, I _{IK} (V _{IN} < 0)	–50 mA
I/O port clamp current, $I_{I/OK}$ ($V_{I/O}$ < 0)	–50 mA
ON-state switch current, I _{I/O} (see Note 4)	±128 mA
Continuous current through V _{CC} or GND terminals	±100 mA
Package thermal impedance, θ _{JA} (see Note 5): D package	73°C/W
(see Note 5): DBQ package	90°C/W
(see Note 5): DGV package	120°C/W
(see Note 5): PW package	108°C/W
(see Note 6): RGY package	39°C/W
Storage temperature range, T _{sta}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to ground, unless otherwise specified.

- 2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 3. V_I and V_O are used to denote specific conditions for $V_{I/O}$.
- 4. I_I and I_O are used to denote specific conditions for I_{I/O}.
- 5. The package thermal impedance is calculated in accordance with JESD 51-7.
- 6. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 7)

		MIN	MAX	UNIT
Vcc	Supply voltage	3	3.6	V
VIH	High-level control input voltage (EN, IN)	2	VCC	V
V _{IL}	Low-level control input voltage (EN, IN)	0	0.8	V
VANALOG	Analog I/O voltage	0	VCC	V
TA	Operating free-air temperature	-40	85	°C

NOTE 7: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



TS3V330 QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH WITH LOW ON-STATE RESISTANCE

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARA	METER		TEST CONDI	TIONS	MIN	TYP†	MAX	UNIT
V_{IK}	EN, IN	$V_{CC} = 3 V$,	$I_{IN} = -18 \text{ mA}$				-1.8	V
٧ _H	EN, IN					150		mV
I _{IH}	EN, IN	$V_{CC} = 3.6 \text{ V},$	V_{IN} and $V_{EN} = V_{CC}$				±1	μΑ
I _I L	EN, IN	$V_{CC} = 3.6 \text{ V},$	V_{IN} and $V_{EN} = GND$				±1	μΑ
loz‡		V _{CC} = 3.6 V,	$V_O = 0 \text{ to } 3.6 \text{ V},$ $V_I = 0,$	Switch OFF			±1	μΑ
l _{OS} §		V _{CC} = 3.6 V,	$V_{O} = 0.5 V_{CC},$ $V_{I} = 0,$	Switch ON	50			mA
I _{off}		$V_{CC} = 0$,	$V_0 = 0 \text{ to } 3.6 \text{ V},$	V _I = 0			15	μΑ
ICC		$V_{CC} = 3.6 \text{ V},$	$I_{I/O} = 0$,	Switch ON or OFF			10	μΑ
∆ICC	EN, IN	$V_{CC} = 3.6 \text{ V},$	One input at 3 V,	Other inputs at V _{CC} or GND			750	μΑ
ICCD		$V_{CC} = 3.6 \text{ V},$ $V_{EN} = \text{GND},$	D and S ports open,	V _{IN} input switching 50% duty cycle			0.45	mA/ MHz
C _{IN}	EN, IN	V_{IN} or $V_{EN} = 0$,	f = 1 MHz			3.5		pF
C	D port	V. – 0	f = 1 MHz,	Switch OFF		10		pF
COFF	S port	$V_{\parallel} = 0$,	Outputs open	SWILCHOFF		5		рг
CON		V _I = 0,	f = 1 MHz, Outputs open	Switch ON		17		pF
. ¶		V2V	V _I = 1 V,	$I_{O} = 13 \text{ mA}, \qquad R_{L} = 75 \Omega$		5	7	Ω
r _{on} ¶		V _{CC} = 3 V	V _I = 2 V,	$I_O = 26 \text{ mA}, \qquad R_L = 75 \Omega$		7	10	22

V_I, V_O, I_I, and I_O refer to I/O pins.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V, R_L = 75 Ω , C_L = 20 pF (unless otherwise noted) (see Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP	MAX	UNIT
ton	S	D		2.5	6.5	ns
tOFF	S	D		1.1	3.5	ns

dynamic characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS			UNIT
D _G #	$R_L = 150 \Omega$,	f = 3.58 MHz, see Figure 6		0.82	%
D _P #	$R_L = 150 \Omega$,	f = 3.58 MHz, see Figure 6		0.1	Deg
BW	R_L = 150 Ω, see Figure 7			300	MHz
XTALK	$R_L = 150 \Omega$,	f = 10 MHz,	R_{IN} = 10 Ω , see Figure 8	-80	dB
O _{IRR}	$R_L = 150 \Omega$,	f = 10 MHz, see Figure 9		-50	dB

 $^{^{\}dagger}$ All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.



[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^{\circ}\text{C}$.

[‡] For I/O ports, IOZ includes the input leakage current.

[§] The IOS test is applicable to only one ON channel at a time. The duration of this test is less than one second.

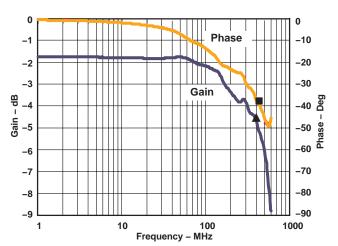
Measured by the voltage drop between the D and S terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (D or S) terminals.

[#]D_G and D_P are expressed in absolute magnitude.

0.08

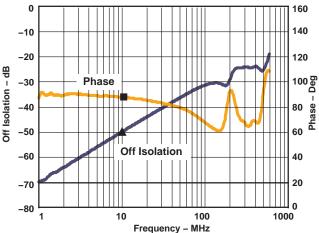
OPERATING CHARACTERISTICS

0.0



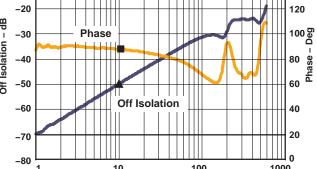
- Gain 3 dB at 400 MHz
- Phase at 3-dB Frequency, -38.28 Degrees

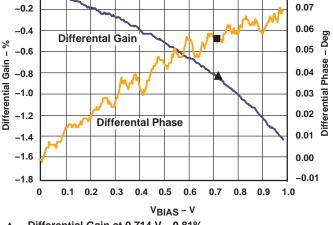
Figure 1. Gain/Phase vs Frequency



- Off Isolation at 10 Mhz, -50.08 dB
- Phase at 10 MHz, 87.8 Degrees

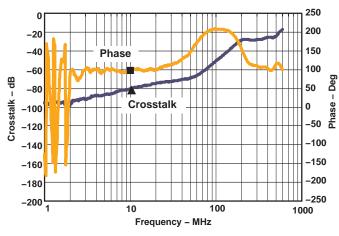
Figure 3. Off Isolation vs Frequency





- Differential Gain at 0.714 V, -0.81%
- Differential Phase at 0.714 V, 0.06 Degree

Figure 2. Differential Gain/Phase vs VBIAS

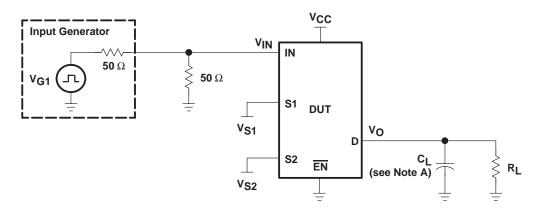


- Crosstalk at 10 MHz, -80 dB
- Phase at 10 MHz, 100.62 Degrees

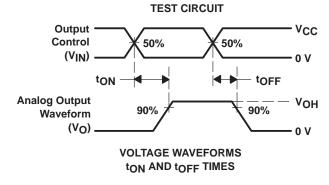
Figure 4. Crosstalk vs Frequency



PARAMETER MEASUREMENT INFORMATION



TEST	VCC	R_{L}	CL	V _{S1}	V _{S2}
ton	$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{3.3 V} \pm \textbf{0.3 V} \end{array}$	75 75	20 20	GND V _{CC}	V _{CC} GND
tOFF	$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{3.3 V} \pm \textbf{0.3 V} \end{array}$	75 75	20 20	GND V _C C	V _{CC} GND



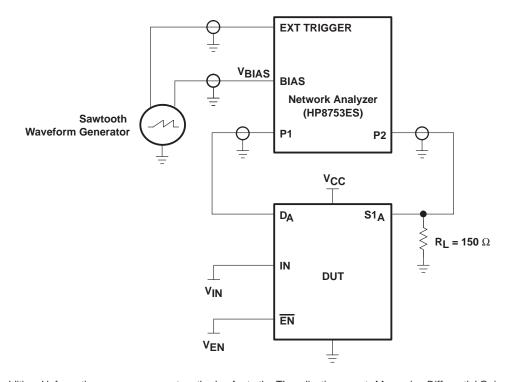
NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- C. The outputs are measured one at a time, with one transition per measurement.

Figure 5. Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



NOTE: For additional information on measurement method, refer to the TI application report, *Measuring Differential Gain and Phase*, literature number SLOA040.

Figure 6. Test Circuit for Differential Gain/Phase Measurement

Differential gain and phase are measured at the output of the ON channel. For example, when $V_{IN} = 0$, $V_{EN} = 0$, and D_A is the input, the output is measured at $S1_A$.

HP8753ES setup

Average = 20

RBW = 300 Hz

ST = 1.381 s

P1 = -7 dBM

CW frequency = 3.58 MHz

sawtooth waveform generator setup

 $V_{BIAS} = 0 \text{ to } 1 \text{ V}$

Frequency = 0.905 Hz



PARAMETER MEASUREMENT INFORMATION

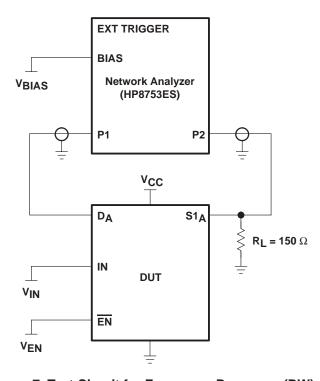


Figure 7. Test Circuit for Frequency Response (BW)

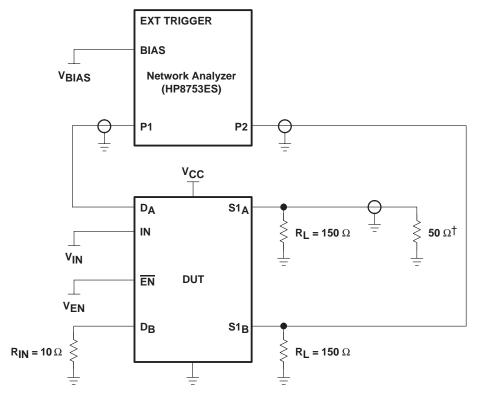
Frequency response is measured at the output of the ON channel. For example, when $V_{IN}=0$, $V_{EN}=0$, and D_A is the input, the output is measured at S1_A. All unused analog I/O ports are left open.

HP8753ES setup

Average = 4 RBW = 3 kHz V_{BIAS} = 0.35 V ST = 2 s P1 = 0 dBM



PARAMETER MEASUREMENT INFORMATION



 \dagger A 50-Ω termination resistor is needed for the network analyzer.

Figure 8. Test Circuit for Crosstalk (X_{TALK})

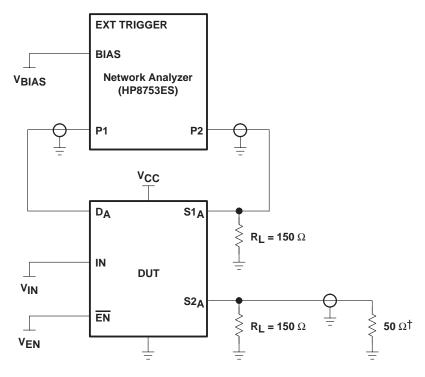
Crosstalk is measured at the output of the nonadjacent ON channel. For example, when $V_{IN}=0$, $V_{EN}=0$, and D_A is the input, the output is measured at S1_B. All unused analog input (D) ports and output (S) ports are connected to GND through $10-\Omega$ and $50-\Omega$ pulldown resistors, respectively.

HP8753ES setup

Average = 4 RBW = 3 kHz $V_{BIAS} = 0.35 V$ ST = 2 s P1 = 0 dBM



PARAMETER MEASUREMENT INFORMATION



† A 50-Ω termination resistor is needed for the Network Analyzer.

Figure 9. Test Circuit for Off Isolation (OIRR)

Off isolation is measured at the output of the OFF channel. For example, when $V_{IN} = V_{CC}$, $V_{EN} = 0$, and D_A is the input, the output is measured at S1_A. All unused analog input (D) ports are left open, and output (S) ports are connected to GND through 50- Ω pulldown resistors.

HP8753ES setup

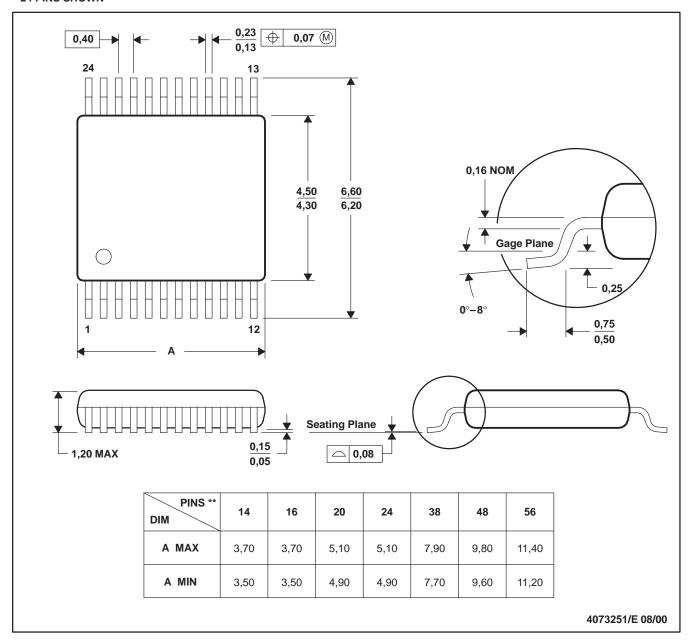
Average = 4 RBW = 3 kHz V_{BIAS} = 0.35 V ST = 2 s P1 = 0 dBM



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



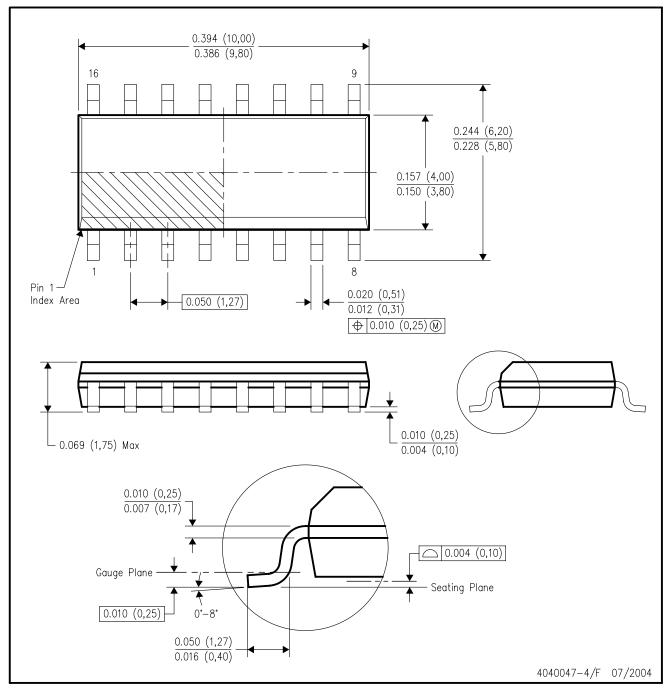
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153 14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

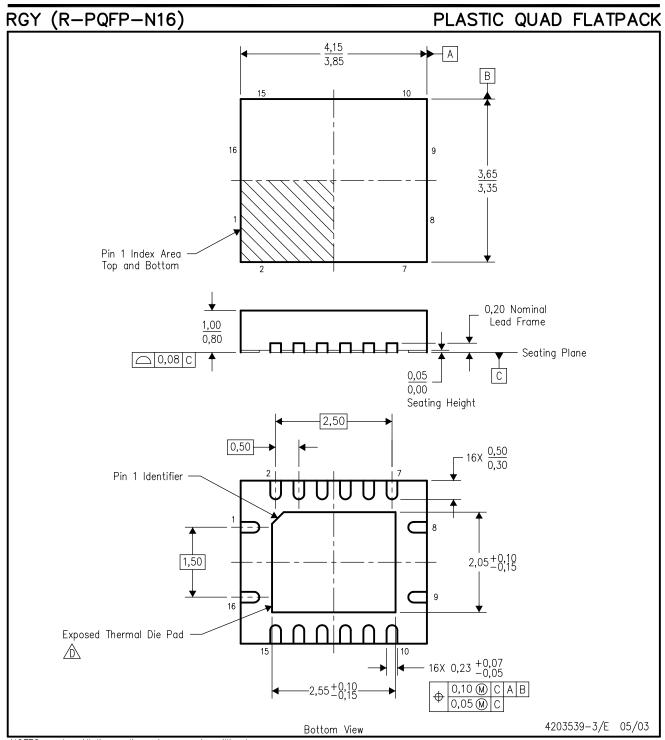
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.





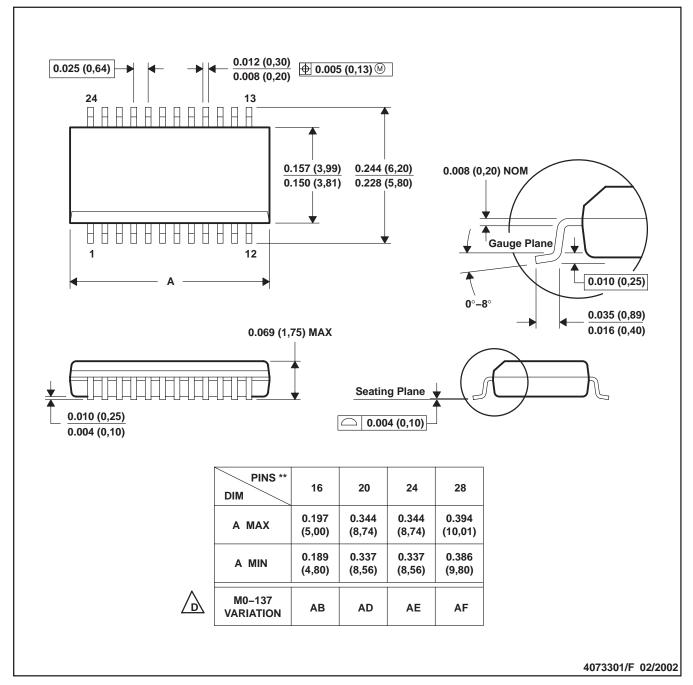
- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane.

 This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BB.



DBQ (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-137.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153

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